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Front Matter: Volume 7221

, "Front Matter: Volume 7221," Proc. SPIE 7221, Photonics Packaging, Integration, and Interconnects IX, 722101 (19 March 2009); doi: 10.1117/12.824593

SPIE.

Event: SPIE OPTO: Integrated Optoelectronic Devices, 2009, San Jose, California, United States

PROCEEDINGS OF SPIE

Photonics Packaging, Integration, and Interconnects IX

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Ray T. Chen

Editors

26-28 January 2009

San Jose, California, United States

Volume 7221

Proceedings of SPIE, 0277-786X, v. 7221

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Author(s), "Title of Paper," in *Photonics Packaging, Integration, and Interconnects IX*, edited by Alexei L. Glebov, Ray T. Chen, Proceedings of SPIE Vol. 7221 (SPIE, Bellingham, WA, 2009) Article CID Number.

ISSN 0277-786X

ISBN 9780819474674

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA

Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445

SPIE.org

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Printed in the United States of America.

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